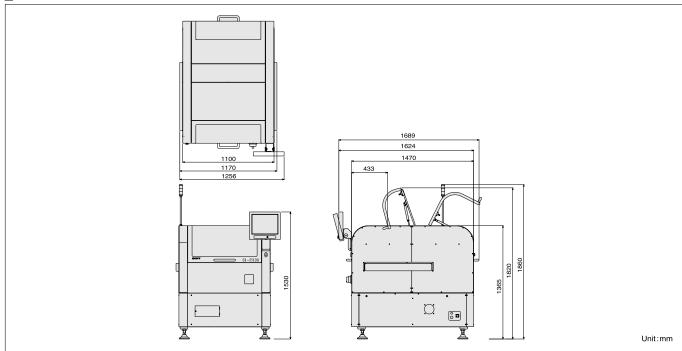
■Main specifications

Model name	SI-P300
Board size	50 x 50 ~ 510 x 460 mm
Board thickness	0.4 ∼ 3.0 mm
Screen size	550 x 650 ~ 750 x 750 x 30 mm (6 types)
Work flow direction	Right to left or left to right
Board position reference	Front or Back
Conveyor height	900 mm (-10 ~ +50 mm)
Printing repeatability	± 20 μm.
Cycle time	10 sec + printing time
OS, Interface	Operating System: Windows, Operator Interface: Touchpanel
Screen cleaning	Full automatic paper cleaning (wet,dry,vacuum) or cloth cleaning (wet,dry)
Power supply / consumption	AC 100 V 50/60 Hz 1.5 kVA (Other power rating optionally available)
Air supply	0.5 MPa
Air consumption	430 Nl/min (Typical 130 Nl/min)
Dimensions	1170 (W) x 1470 (D) x 1530 (H) mm (Machine status light height 1860mm)
Weight	870 ka

External view



______ Safety Notice: For your safety, please read the instruction manual carefully before using the product.

•Specifications and appearance are subject to change without prior notice. •Windows⁰ is a trademark of Microsoft Corporation.

Sony Manufacturing Systems Corporation

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http://www.sonysms.co.jp/ The contents of this literature are as of Oct.2005 Sony Electronics (Singapore) Pte. Ltd. Sony Precision Engineering Center No.52 Tuas Avenue 9 Singapore 639193 Tel: +65-6

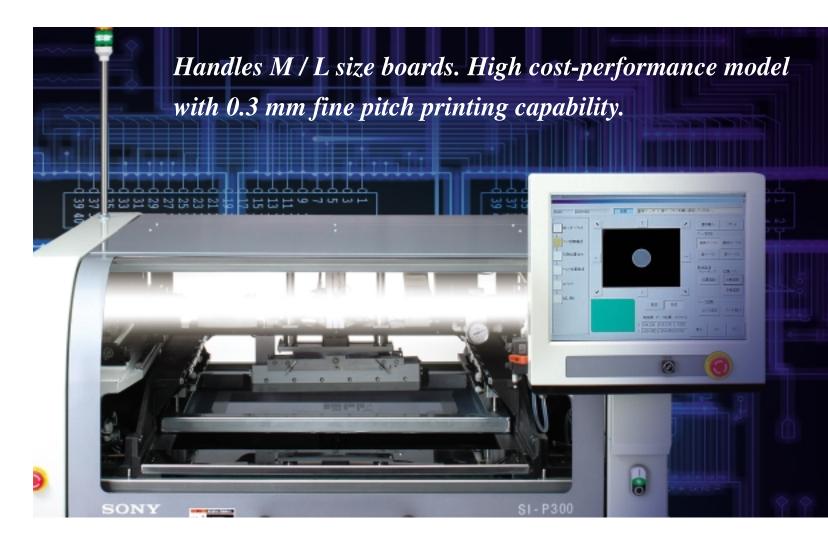
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Used material: 100% recycled paper, recyclable Zero-VOC (Volatile Organic Compound) vegetable oil ink 015E-0510-06-01A

SONY

Solder Paste Printer SI-P300



Solder Paste Printer



Handles M / L size PWBs to flexibly adapt even for frequent changeover. In addition to high-precision and good solder squeegee capability, every effort has been made to maximize the ease of use at the production site.

From small boards for mobile devices, such as cellular phones to large boards for home electronics and information systems such as TVs and PCs, the SI-P300 is an excellent cost-performance, high-precision solder paste printer that can handle production of many types of PWBs with one unit. In addition to offering 0.3 mm fine pitch printing, there is an automatic cleaning function to simplify maintenance, and a touchpanel to provide easy operation.

The SI-P300 delivers an easy to use system for high-quality PWB production.

High-precision printing with print precision of \pm 20 μ m, and 0.3 mm fine pitch

By using dedicated designed rigid frame table and high-accuracy AC servo repeatability is ± 20 µm and can print for fine pitch component such as BGA (\emptyset = 0.28 mm, P = 0.3 mm) and QFP (P = 0.3mm) which requires high preciseness





Stable solder fill rates by perfect plate removal.

Vacuum and two stage plate removal is used for the board removal mechanism. Using high-precision servomotors to control the board removal provides excellent printing results.



Vision Inspection equipped for post-print inspection

A CCD camera unit is built in to provide afterprint inspection function. In addition to detecting solder points, it is also possible to check solder misalignment, deformation, etc. Easy 100-point inspection allows reliable monitoring of product quality.







Automatic stencil cleaning function using roll paper or cloth

In addition to the conventional rollpaper cleaning method, SI-P300 offers a cloth cleaning method that rivals cleaning either method, including wet method, dry method, suction, and number of repetitions.







Easy operation by touch panel interface and multi language support





